Form PTO-1595 RECORDATION FORM COVER SHEET (Rev. 10/02) U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office OMB No. 0651-0027 (exp. 6.30.2005) PATENTS ONLY	
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.	
Name of conveying party(ies):	Name and address of receiving party(ies)
Cheng-Hung Lee, Ching-Hwi Wu and Hung-Jen Liao	Name: Talwan Semiconductor Manufacturing Co., Ltd.
<u> </u>	Internal Address:
Additional name(s) of conveying party(ies) attached? ☐ Yes ☒No	Street Address: No. 8, Li-Hsin Road 6
3. Nature of conveyance:	Science Based Industrial Park
Assignment □ Merger The state of t	City: Hsin-Chu State: Taiwan Zip: 300-77
☐ Security Agreement ☐ Change of Name	<u> </u>
☐ Other	Additional name(s) & address(es) attached?
Execution Date: April 23 and 30, 2008	□ Yes ⊠No
Application number(s) or patent number(s):	
If this document is being filed together with a new application, the execution date of the application is: April 29, 2008	
A. Patent Application No.(s)	B. Patent No.(s)
12/111,905	
Additional numbers attached? ☐ Yes ☒ No	
Name and address of party to whom correspondence concerning document should be mailed:	Total number of applications and patents involved: 1
Name: <u>Howard Chen, Esq.</u>	7. Total fee (37 CFR 3.41)\$ 40.00
Internal Address:	
"	Enclosed
Street Address: <u>Kirkpatrick & Lockhart Preston</u>	X Authorized to be charged to deposit account
Gates Ellis LLP	1
55 Second Street, Suite 1700	
City: San Francisco State: CA Zip: 94105	8. Deposit account number:
1	50-3414
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9. Signature:	
Howard Chen, Esq.	5/13/2008 Date
Reg. No. 46,615	Date
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Commissioner of Patents & Trademarks, Box Assignments

Washington, D.C. 20231

PATENT REEL: 020946 FRAME: 0379

Attorney Reference No.: 52604-00288

Patent Attorney Docket No.: TSMC2007-0604

ASSIGNMENT AND AGREEMENT

For value received, I/we Chang-Hung Lee, Ching-Hwi Wu and Hung-Jen Liao, hereby equally sell, assign and transfer to Talwan Semiconductor Manufacturing Co., Ltd., with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and their successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to NOVEL SRAM CELL ARRAY STRUCTURE described in U.S. Application Number 12/111,905 for Letters Patent of the United States filed on Apr 11 29 2008 and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and I/we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I/We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me/us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I/We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of **Taiwan Semiconductor Manufacturing Co.**, Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I/We request that any and all patents for said inventions be issued to Talwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Talwan Semiconductor Manufacturing Co., Ltd. may designate.

I/We agree that, when requested, I/we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Assignment and Agreement - Page - 1 -

PATENT REEL: 020946 FRAME: 0380

Mailing and Residence: 8F-2, No. 32, Ti-Yu Street, Hsin-Chu City, Taiwan, ROC

Citizenship: Talwan

Assignment and Agreement -- Page - 2 -

PATENT REEL: 020946 FRAME: 0381 MAKE COLUMN BUILD CONTROL

Attorney Reference No.: 52604-00288 Patent Attorney Docket No.: TSMC2007-0604 Inventor No. 1: Dated: Cheng-Hung Lee Mailing and Residence: 257, min-shong Rd. Hukou Village, Heinchu, Taiwan R.O.C. Citizenship: Taiwan Inventor No. 2: Ching - Wei Wu 异级度 Ching-Wei Wu Dated: $\frac{4}{3}$, $\frac{240}{3}$ Mailing and Residence: 9, Creation Rd. 1, Science-Based Industrial Park, Hsin Chu, Taiwan R.O.C. Citizenship: Taiwan Inventor No. 3: Dated: Hung-Jen Liao Mailing and Residence: 8F-2, No. 32, Ti-Yu Street, Hsin-Chu City, Taiwan, ROC

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PATENT REEL: 020946 FRAME: 0382

Citizenship: Taiwan